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Country	Taiwan, R.O.C.

## PRODUCTS OR MACHINERY

**Technology** is our cornerstone. Innovation is our passion. We place more resources against what we do than anyone else in the industry. As the industry's largest semiconductor foundry, TSMC places quality and precision above all else to create market leading integrated circuit wafers.

### Advanced Technology

TSMC provides the foundry industry's leading advanced process technologies and design collaterals. These processes include 40nm, 55nm, 65nm, 90nm and 0.13-micron. TSMC's advanced process technology provides the optimal combination of gate density, speed, and power, making it ideal for a broad range of applications such as computing, communications, and consumer electronics. On top of each node supports logic designs, mixed-signal/RF while embedded DRAM option is available for 40nm, 65nm and 90nm. Design collaterals include TSMC internal macros and the world's largest third-party IP library portfolios.

Much of the work of TSMC's Open Innovation Platformtm is target to advanced technology deployment. It is the collaborative nature of the Open Innovationtm model that brings together the best technical thinking of partners and customers alike that have driven TSMC's reputation of ramping advanced technology processes at the leading edge of the adoption curve.

TSMC advanced technology is significantly ahead of the ITRS roadmap. The company delivers a new advanced technology generation every two years. Each node surpasses the previous one by close to half the area and usually features 30 to 50 percent more performance, while supporting similar leakage levels. TSMC provides substantial advanced technology capacity by ramping the same node at multiple 300mm GigaFabs that, when they reach full capacity, will produce over 100,000 12-inch wafers per month.

### Mainstream Technology

TSMC's mainstream technology platform supports the industry's richest technology mix, unmatched manufacturing excellence, and a robust portfolio of time-to-volume focused foundry services.

Front-end design  
Mask and prototyping services  
Backend packaging and test services  
Front-to-back on-line logistics

All these services and more provide industry-leading yields, quality, and manufacturing cycle times.

### Feature Technology

In this era of omnipresent design differentiation, TSMC is proactively taking step to satisfy the semiconductor industry's needs. No longer is a logic focused process technology able to meet all market requirements. Rather, today's industry innovator requires special feature technologies such as mixed-signal/RF, embedded high density memory, non-volatile memory, high voltage devices and CMOS image sensor technologies. Feature technologies span TSMC's Advanced and Mainstream Logic Technology platforms. All feature technologies are supported down to the 0.18-micron process node. Embedded high density memory is available in Advanced Technology platforms down to the 0.13-micron node. Mixed signal technology is available down to the 90nm process node. Together, TSMC's feature technologies, integrated with their corresponding logic technologies provide a total platform solution meeting the industry's broadest range of IC design requirements.

### Company Profile of Taiwan Semiconductor Manufacturing Company Limited

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